

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-35 (canceled)

Claim 36 (previously presented): A device transfer method comprising:
embedding one-side devices into an uncured pressure sensitive adhesive layer provided on a second substrate;

embedding other-side devices arranged on a first substrate into the uncured pressure sensitive adhesive layer provided on the second substrate wherein the other-side devices and one-side devices are light emitting diodes having different characteristics; and

stripping the other-side devices from the first substrate thereby holding the other-side devices in an embedded state in the uncured pressure sensitive adhesive layer.

Claim 37 (canceled)

Claim 38 (previously presented): The device transfer method as set forth in claim 36, wherein the one-side devices and the other-side devices are held in the embedded state in different areas on the substrate.

Claim 39 (currently amended): A method of manufacturing a display apparatus ~~obtained by a method~~ comprising:

embedding devices arranged on a first substrate into a pressure sensitive adhesive layer provided on a second substrate wherein the devices are light emitting diodes, the pressure sensitive adhesive layer being in an uncured state;

stripping the devices from the first substrate thereby holding the devices in an embedded and uncured state in the pressure sensitive adhesive layer,

hardening the pressure sensitive adhesive layer to cure the pressure sensitive adhesive layer;

forming first electric wirings on the pressure sensitive adhesive layer, adhering a third substrate onto a side on which the first electric wirings are formed of the pressure sensitive adhesive layer, and stripping the second substrate and the pressure sensitive adhesive layer from each other; and

providing the pressure sensitive adhesive layer with openings reaching the devices, filling the openings with a conductive material, and forming second electric wirings on the pressure sensitive adhesive layer.

Claim 40 (currently amended): The method of manufacturing a display apparatus as set forth in claim 39, wherein display is carried out through simple matrix driving by impressing a voltage on the devices through the first electric wirings and the second electric wirings.

Claim 41 (currently amended): A method of manufacturing a display apparatus ~~obtained by a method~~ comprising:

embedding one-side devices arranged on a first substrate into a pressure sensitive adhesive layer provided on a second substrate, the pressure sensitive adhesive layer being in an uncured state;

stripping the one-side devices from the first substrate thereby holding the one-side devices in an embedded and uncured state in the pressure sensitive adhesive layer;

further embedding other-side devices arranged on the first substrate into the pressure sensitive adhesive layer, the pressure sensitive layer being remaining in an uncured state;

stripping the other-side devices from the first substrate thereby holding the other-side devices in an embedded and uncured state in the pressure sensitive adhesive layer, where the one-side devices are embedded in the uncured pressure sensitive adhesive layer, and wherein the one-side devices and other-side devices are light emitting diodes;

hardening the pressure sensitive adhesive layer to cure the pressure sensitive adhesive layer where the one-side devices and the other-side devices are held in an embedded and cured state in the pressure sensitive adhesive layer;

forming first electric wirings on the pressure sensitive adhesive layer, adhering a third substrate onto the side on which the first electric wirings are formed of the pressure sensitive

layer, and stripping the second substrate and the pressure sensitive adhesive layer from each other; and

providing the pressure sensitive adhesive layer with openings reaching the one-side devices or the other-side devices, filling the openings with a conductive material, and forming second electric wirings on the pressure sensitive adhesive layer.

Claim 42 (currently amended): The method of manufacturing a display apparatus as set forth in claim 41, wherein the one-side devices and the other-side devices have different characteristics.

Claim 43 (currently amended): The method of manufacturing a display apparatus as set forth in claim 41, wherein the one-side devices and the other-side devices are held in the embedded state in different areas on the second substrate.

Claim 44 (currently amended): The method of manufacturing a display apparatus as set forth in claim 41, wherein display is carried out through simple matrix driving by impressing a voltage on the one-side devices or the other-side devices through the first electric wirings and the second electric wirings.

Claim 45 (currently amended): The method of manufacturing a display apparatus as set forth in claim 41, wherein any one of the one-side devices and the other-side devices are any one of display devices and driving circuit devices.

Claim 46 (currently amended): The method of manufacturing a display apparatus as set forth in claim 45, wherein display is carried out through active matrix driving by impressing a voltage on the display devices by the driving circuit devices.

Claim 47 (previously presented): The device transfer method as set forth in claim 36, further comprising bringing the other-side devices into contact with a temporary adhesion layer provided on the first substrate for temporarily adhering the devices to the temporary adhesion layer thereby arranging the devices on the first substrate, before embedding the other-side devices into the uncured pressure sensitive adhesive layer provided on the second substrate.

Claim 48 (previously presented): The device transfer method as set forth in claim 47, wherein a tack of the pressure sensitive adhesive layer provided on the second substrate is greater than a tack of the temporary adhesion layer provided on the first substrate.

Claim 49 (previously presented): The device transfer method as set forth in claim 48, wherein the tack of at least one of the uncured pressure sensitive adhesive layer and the temporary adhesion layer is changed so that the tack of the uncured pressure sensitive adhesive layer will be greater than the tack of the temporary adhesion layer.

Claim 50 (previously presented): The device transfer method as set forth in claim 36, further comprising curing the uncured pressure sensitive adhesive layer using a heating treatment.

Claim 51 (currently amended): The method of manufacturing a display apparatus of claim 39, wherein the uncured pressure sensitive adhesive layer is hardened after stripping the devices from the first substrate.